

VM214

4-CHANNEL, THIN-FILM HEAD READ/WRITE PREAMPLIFIER

July, 1992

FEATURES

- For Use with Non Center-Tapped Thin-Film Heads
- . Supports Four Read / Write Heads Per Circuit
- · Complete Fault Detect Capability
- . On-Chip Current Source, Externally Adjusted
- · TTL-Compatible Control Signals
- · Very Low Input Noise
- High Gain

DESCRIPTION

The VM214 is an integrated read/write preamplifier designed for use with non center-tapped thin-film heads. Each circuit controls four heads and has three modes of operation: read, write, and idle. The circuit functions as a low-noise differential amplifier in the read mode and as a differential current switch in the write mode. Write current is supplied by an internal current source. The magnitude of the write-current to the heads is determined by an external resistor. The VM214 operates on +5V and -5V and is available in 24-lead flatpack ap SOIC packages.

ABSOLUTE MAXIMUM RATINGS

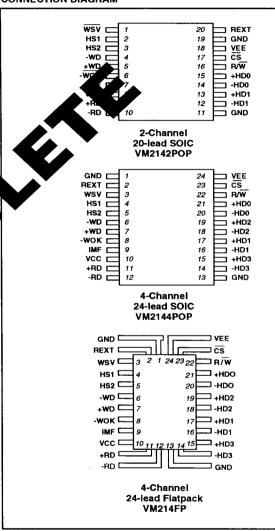
Power Supply Voltages:

V _{CC} 6V V _{EE} -6V Input Voltages: -6V Head Select (HS1, HS2) 0 V _{CC} + 0.3V Chip Select (CS) -0.4V to V _{CC} + 0.3V Read/Write Select (RW) -0.4V to V _{CC} + 0.3V Write Data (WD) -0.6V to 0.4V Output Levels: Read Inputs, Read Mode (+HDN) -0.6V to 0.4V Read Data (+RD) V _{CC} - 2.5V to V _{CC} + 0.3V and 20mA Write OK (WOK) -0.4V to V _{CC} + 0.3V and 20mA Write Select Verifty (WSV) -0.4V to V _{CC} + 0.3V and 20mA Current Monitor (IMF) 0.4V to V _{CC} + 0.3V and 8mA Head Outputs, Write Mode (±HDN) IW max. = 150mA Storage Temperature Range -65° to 150°C Lead Temperature (Soldering 60 Sec.) 300°C Operating Temperature 70°C Junction Temperature 150°C Thermal Characteristics Θ _{JA} : 20-lead SOIC 80°C/W 24-lead SOIC 80°C/W 24-lead Flatpack 110°C/W	
Input Voltages:	V _{CC} 6V
Head Select (HS1, HS2)	V _{EE} 6V
Chip Select (CS)	Input Voltages:
Read/Write Select (R/W) -0.4V to V _{CC} + 0.3V Write Data (WD) -V _{EE} to 0.3V Read Inputs, Read Mode (+HDN) -0.6V to 0.4V Output Levels: Read Data (+RD) V _{CC} - 2.5V to V _{CC} + 0.3V and 20mA Write OK (WOK) -0.4V to V _{CC} + 0.3V and 20mA Write Select Verifty (WSV) -0.4V to V _{CC} + 0.3V and 20mA Current Monitor (IMF) 0.4V to V _{CC} + 0.3V and 8mA Head Outputs, Write Mode (±HDN) IW max. = 150mA Storage Temperature Range -65° to 150°C Lead Temperature (Soldering 60 Sec.) 300°C Operating Temperature 70°C Junction Temperature 150°C Thermal Characteristics Θ _{JA} : 20-lead SOIC 80°C/W 24-lead SOIC 80°C/W	Head Select (HS1, HS2)
Write Data (WD)	Chip Select (CS)
Read Inputs, Read Mode (+HDN)	Read/Write Select (R/W)0.4V to V _{CC} + 0.3V
Output Levels: Read Data $(+RD)$	Write Data (WD)V _{FF} to 0.3V
$\begin{array}{llllllllllllllllllllllllllllllllllll$	Read Inputs, Read Mode (+HDN)
Write OK ($\overline{\text{WOK}}$)	Output Levels:
Write Select Verifty (WSV)0.4V to V_{CC} + 0.3V and 20mA Current Monitor (IMF) 0.4V to V_{CC} + 0.3V and 8mA Current Reference (R_{EXT}) V_{EE} to V_{CC} + 0.3V and 8mA Head Outputs, Write Mode (\pm HDN) IW max. = 150mA Storage Temperature Range65° to 150°C Lead Temperature (Soldering 60 Sec.) 300°C Operating Temperature 70°C Junction Temperature 150°C Thermal Characteristics Θ_{JA} : 20-lead SOIC 80°C/W 24-lead SOIC 80°C/W	Read Data (+RD) V _{CC} - 2.5V to V _{CC} + 0.3V
Write Select Verifty (WSV)0.4V to V_{CC} + 0.3V and 20mA Current Monitor (IMF) 0.4V to V_{CC} + 0.3V and 8mA Current Reference (R_{EXT}) V_{EE} to V_{CC} + 0.3V and 8mA Head Outputs, Write Mode (\pm HDN) IW max. = 150mA Storage Temperature Range65° to 150°C Lead Temperature (Soldering 60 Sec.) 300°C Operating Temperature 70°C Junction Temperature 150°C Thermal Characteristics Θ_{JA} : 20-lead SOIC 80°C/W 24-lead SOIC 80°C/W	Write OK (WOK)0.4V to V _{CC} + 0.3V and 20mA
Current Monitor (IMF)	
Current Reference (R _{EXT})V _{EE} to V _{CC} + 0.3V and 8mA Head Outputs, Write Mode (±HDN) IW max. = 150mA Storage Temperature Range65° to 150°C Lead Temperature (Soldering 60 Sec.) 300°C Operating Temperature 70°C Junction Temperature 150°C Thermal Characteristics Θ _{JA} : 20-lead SOIC 80°C/W 24-lead SOIC 80°C/W	
Head Outputs, Write Mode (±HDN) IW max. = 150mA Storage Temperature Range65° to 150°C Lead Temperature (Soldering 60 Sec.) 300°C Operating Temperature 70°C Junction Temperature 150°C Thermal Characteristics Θ _{JA} : 20-lead SOIC 80°C/W 24-lead SOIC 80°C/W	
Storage Temperature Range -65° to 150°C Lead Temperature (Soldering 60 Sec.) 300°C Operating Temperature 70°C Junction Temperature 150°C Thermal Characteristics Θ _{JA} : 80°C/W 20-lead SOIC 80°C/W 24-lead SOIC 80°C/W	
Lead Temperature (Soldering 60 Sec.) 300°C Operating Temperature 70°C Junction Temperature 150°C Thermal Characteristics Θ _{JA} : 80°C/W 20-lead SOIC 80°C/W 24-lead SOIC 80°C/W	Storage Temperature Range65° to 150°C
Operating Temperature 70°C Junction Temperature 150°C Thermal Characteristics Θ _{JA} : 80°C/W 20-lead SOIC 80°C/W 24-lead SOIC 80°C/W	
Thermal Characteristics Θ _{JA} : 80°C/W 20-lead SOIC 80°C/W 24-lead SOIC 80°C/W	
20-lead SOIC 80°C/W 24-lead SOIC 80°C/W	Junction Temperature150°C
24-lead SOIC 80°C/W	Thermal Characteristics O,IA:
	20-lead SOIC 80°C/W
24-lead Flatpack	24-lead SOIC 80°C/W
	24-lead Flatpack

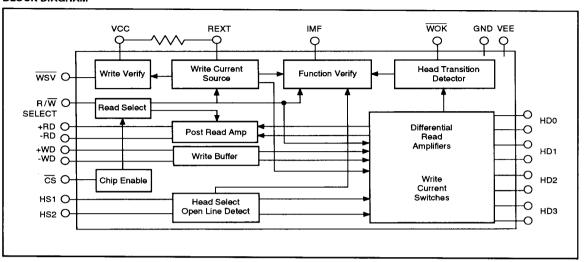
RECOMMENDED OPERATING CONDITIONS

DC Power Supply Voltage:	
V _{CC}	5V ± 5%
Negative Supply Voltage (VEE)	5V ± 5%
Head Load (L _H)	. 150 - 600µH
Junction Temperature	25° to +125°C

CONNECTION DIAGRAM



BLOCK DIAGRAM



CIRCUIT OPERATION

The VM214 has four channels of read amplifiers and write drivers plus an internal write current source. The write current magnitude is determined by an external resistor (R_{EXT}) connected between pins R_{EXT} and V_{CC} . The VM214 has the following TTL-compatible control lines:

- The chip select (CS) input selects the active or the idle mode. The idle mode allows circuits to be multiplexed.
- 2. If the chip is active (enabled), the read/write select (R/W) input is used to select the read or write modes.
- The head select inputs (HS1, HS2) select one of the four channels for a read or write operation.

The write data (\pm WD) input voltage range includes the ECL levels. The read (\pm RD) outputs are open collector, requiring external 100 Ω (R_L) load resistors connected to V_{CC}.

Write Mode

In the write mode, the VM214 functions as a differential current switch channeling the write current to the selected head determined by HS1 and HS2. The write data inputs (±WD) determine the polarity of the head current. The write current is supplied by an internal current source and the magnitude is determined by the value of an external resistor connected between V_{CC} and the R_{EXT} pin.

Read Mode

In the read mode, the circuit operates as a low noise differential amplifier. Pins HS1 and HS2 determine which differential input channel is selected and applied to the amplifier. The amplifier output is read differentially at the read data (\pm RD) pins.

Fault Detection

The chip contains fault <u>detection</u> circuits. A high level at an enabled chip's write OK (WOK) output is caused by the following write fault conditions:

- 1. Chip not enabled
- 2. Open head
- 3. Non-switching write data (±WD)
- 4. No write current (can be in read mode)
- 5. Open head select inputs (HS1, HS2)
- 6. Head shorted to ground
- 7. Write frequency is outside of limits
- 8. Chip in read mode

When a chip is enabled the IMF current monitor provides a 3mA output. This feature allows single or multichip enabled conditions to be detected.

An open collector output, write select verify (\overline{WSV}), goes low when the chip has write current present.

PIN DESCRIPTIONS

Read Data Outputs

Read data outputs (\pm RD) consist of a pair of differential lines used to pass the amplified read signal (30 to 100mVp-p signals-typical) to the disk drive electronics. External 100 Ω load resistors tied to V_{CC} are required.

Write Data Inputs

Write data inputs (\pm WD) consist of a pair of differential lines used to write high frequency data patterns onto the disk via the selected R/W head and chip. Input data levels can either be driven directly from ECL level drivers with proper termination resistances or from open collector current drivers terminated into 100Ω resistors to ground.

Chip Select Input (CS)

Chip select input (CS) is a TTL-compatible input line used to enable or disable the VM214. The chip enable input requires an open collector TTL-compatible drive source. A logic low enables the chip, while a logic high or open cable disables the chip by putting it into an idle state.

Read/Write Select Input (R/W)

The read/write select input (R/W) is a TTL-compatible input line used to select either the read or write mode of operation when the chip has been enabled (CS = 0V). A logic high state or open cable selects the read mode of operation while low state selects the write mode of operation.

Write Select Verify Output (WSV)

The write select verify (WSV) output is an open-collector, TTL-compatible output that is used to verify that write current is present. The output is terminated into a user-determined resistor to +5V. A logic low state indicates that write current is present.

Current Monitor Output (IMF)

The current monitor (IMF) output is an open-collector current output that is used to indicate the chip is in the active or enabled mode. Output is terminated into a user-determined resistance to +5V.

Nominal "safe" current is 3mA for one chip enabled. If the IMF current falls below 2mA, a "no function" error is detected in the drive electronics indicating the chip selected has not been enabled or the chip is defective. If more than 4mA is detected a "multi-function" error is generated in the disk drive electronics. This indicates that more than one chip has been activated, the chip selected is defective or the IMF line is shorted to ground or negative voltage.

Write OK Output (WOK)

The write OK (WOK) output is an open-collector, TTL-Compatible output that is used to indicate an open head, no write data, no write-current or open head select (HS1, HS2) condition exists. The WOK output is terminated into a user-determined resistor to +5V. A logic low indicates a "safe" condition while a logic high indicates a "fault" condition.

Head Select Inputs (HS1, HS2)

The head select inputs (HS1,HS2) are bussed TTL-Compatible logic control signals used to select one of four R/W channels on a selected chip (0.8V). An open HS1 or HS2 input will give a fault indication to the disk drive electronics via write OK (WOK).

Table 1: Head Select

HS2	HS1	HEAD
L	L	0
L	Н	1
н	L	2
Н	Н	3

Table 2: Mode Select

CS	R/W	MODE
L	L	Write
L	Н	Read
н	L	Idle
Н	Н	idle

Table 3: External Resistor vs. Write Current

External resistor vs. DC write current I winto the selected head terminal X or Y with V _{CT} shorted only to the respective X or Y terminal.						
1% External Resistor	Write Current					
R _{WC} (Ω)	I W (mA)					
6.9	10					
4.0	20					
2.7	30					
2.0	40					
1.6	50					

DC CHARACTERISTICS

Unless otherwise specified, V_{CC} = 5 ± 0.01V, V_{EE} = -5V ±0.01V, T_A = 25°C.

PARAMETER	SYM	CONDITIONS	MIN	TYP	MAX	UNITS
5 6 . 6		Read			56	mA
Positive Supply Current lw = 40mA	l _{CC}	Write		***	50	mA
•		ldle			12	mA
		Read			-85	mA
Negative Supply Current I w = 40mA	1 _{EE}	Write			-165	mA
144 - 4011114		ldle			-15	mA
5 5: ::		Read			670	mW
Power Dissipation I _W = 40mA	PD	Write			1.05	W
W = 75.1131		Idle]		140	mW
Digital TTL Inputs	VH	High Voltage	2	3.5	4	V
(CS, RW, HS1, HS2)	٧L	Low Voltage		0.2	0.8	V
Digital ECL Inputs	VH	High Voltage			-0.6	V
(±WD)	٧L	Low Voltage			-1.5	٧
Chin Salast Comment	¹ CSH	High; VCSH = 4V			-0.3	mA
Chip Select Current	CSL	Low; VCSL = 0.4V			-1.4	mA
R/W Select Current	IRSH	High; VR/WH = 4V (RM)			-15	μА
TV VV Select Current	¹ RSL	Low; VR/WL = 0.4V (WM)			-200	μА
Head Select Current	IHSH	High; VHSH = 4V			250	μА
(HS1, HS2)	HSL	Low; VHSL = 0.4V			250	μА

FAULT DETECTION CHARACTERISTICS

Unless otherwise specified, V_{CC} = 5 ± 0.01V, V_{EE} = -5V ±0.01V, T_A = 25°C.

PARAMETER		SYM	CONDITIONS	MIN	TYP	MAX	UNITS
Write Select	Write Select High (Unsafe)		IW_= 80mAp-p, CS = VCSL,	4.9			٧
Verify Voltage	Low (Safe)	VWSVL	$R/W = V_{R}/\overline{W}_{L}$, $R_{L} = 750\Omega$ min.			400	mV
Write OK	High (Unsafe)	Vwokh	$\overline{\text{CS}} = \text{V}_{\text{CSL}}$, $\text{R/W} = \text{V}_{\text{R/WL}}$, min. $\text{R}_{\text{L}} = 750\Omega$ min.	4.9			V
Voltage	Low (Safe)	VWOKL				400	mV
IMF Current Chi	p Enable (ON)	IMF	$\overline{CS} = V_{CSL}$, read or write mode, R _L = 1K Ω to 5V	-2.2		3.7	mA
IMF Voltage Chi	ip Disable (OFF)	VIMF	CS = VCSL , R L = 1KΩ to 5V	4.9			V
Write Select Ver	fiy Delay Time						
Read to Write Mode (ON)		tWSON	CS = V _{CSI}			600	ns
Write to R	ead Mode (OFF)	[†] WSOFF	co = ACSF				"

READ CHARACTERISTICS

Unless otherwise specified, V_{CC} = 5 ± 0.01V, V_{EE} = -5V ±0.01V, T_A = 25°C.

PARAMETER	SYM	CONDITIONS	MIN	TYP	MAX	UNITS
Differential Voltage Gain	A _V	R _L = 100Ω each side to V _{CC} , f = 1MHz, input V _{IN} = 1mVrms	100		150	V/V
Bandwidth	BW	RL = 100Ω each side. Zs = 2.4Ω , $V_{IN} = 1$ mVrms, fMIDBAND = 300 KHz				
-3 dB			35		100	MHz
-1 dB			15			
Input Noise Voltage	ein	$V_{ N} = 0V$, PWR BW = 17MHz, R _L = 100 Ω each side.			1,1	nV/√Hz
Differential Input Capacitance	CIN	$V_{IN} = 0V$, $f = 5MHz$			65	pF
Differential Input Resistance	R _{IN}	$V_{ N} = 0V$	1330		2470	Ω
Voltage Gain Linearity	A _{VL}	AC input voltage where the gain is 90% of the gain with 0.2mVrms Input, f = 1MHz, R $_{\rm L}$ = 100 Ω each side to VCC.			± 2	mV
Common Mode Rejection Ratio 1MHz ≤ f ≤ 10MHz	CMRR	CMPR = $20 \cdot \log (A_V / [V_O / V_{CM}])$ $V_{CM} = 100 \text{mVp-p}$	50			dB
f = 20MHz		Input Referred	46			
Power Supply Rejection Ratio $f = 1 \text{MHz}$ $f = 20 \text{MHz}$	PSRR	VIN = VEE + 100mVp-p OR V _{CC} + 100mVp-p PSRR = 20 · log (A y/ [V _{OUT} /V _{IN}])	65			dB
Channel Separation	cs	Selected Head V _{IN} = 0V	40			
(Read Crosstalk)	63	Unselected Heads V _{IN} = 0V Unselected Heads V _{IN} = 20mVp-p				
` 1MHz ≤ f ≤ 10MHz		"\	46			dB
f = 20MHz	1		40			
Output Offset Voltage	Vos	R _L = 100Ω each side to V _{CC}	-360		360	mV
Common Mode Output Voltage	Vосм	R _L = 100Ω each side to VCC	V _{CC} - 0.9		V _{CC} - 0.3	٧
Output Leakage Current (Idle Mode)	loL				10	μА

PARAMETE	R	SYM	CONDITIONS	MIN	TYP	MAX	UNITS
Write Current Rang	ge	١w		10		50	mA
Current Tolerance		^I WT	Current set to nominal value by external 1% resistor (R EXT). RH = $20\Omega \pm 1\%$	-8		8	%
Head Differential Le Resistance	oad	RDL		1330		2470	Ω
Head Differential Lo Capacitance	oad	CDL				10	pF
Head Current	Rise Time	tr	$RH = 20\Omega$, Measure t _f 10% to 90% of transition. Measure t _f 90% to 10% of				
riodd Odireik	Fall Time	t _f				16	ns
Current Gain		Aj			20		mA/mA
Head Current Switch	ching Delay	[†] HC	IW = 40mA, LH = 150nH, R_H = 20Ω, Measured from 50% of write data to 50% transition of write current (IW)			18	ns
Head Current Switch Delay Difference	ching		f = 3MHz (Write Data)			1	ns
Write Crosstalk (Ur Head Current	nselected	W _{XT}	IW = 40mA, LH = 150nH, R _H = 20Ω maximum. Measured unselected channels while driving selected channels			2	mA peak
Head Current Switc Time-Symmetry		^t SYM	V_{WDD} = 200mV, I_{W} = 40mA I_{H} = 150nH, I_{H} = 20Ω max. ±WD transition = 2ns ±WD symmetry = 0.2ns			1.5	ns
Differential Data Vo	oltage	VWDD		200			mV
Write Data Input Vo	oltage Range	V _{WD}		-2.5		0.1	V
Data Input Current	(per side)	l WD	CS = V _L = 0V			150	μА
Write Current Overs	shoot B/A	Iwos	$l_W = 40 \text{mA}, L_H = 150 \text{nH}, R_H = 20 \Omega$		_	20	%

SWITCHING CHARACTERISTICS C_L (RDX, RDY) \leq 20pF, T_A = 25°C.

Unless otherwise specified, I_W = 40mA, L_H = 2.5 μ H, R_D = 750 Ω , f_{DATA} = 5MHz,

Chip Select Delay					UNITS
lelle to Milita		Measure delay to 90% of 5MHz.			
ldle to Write	tıw	Read Output or Write Current		1	
Idle to Read	tIB			 600	μs ns
Chip Select Delay		Measure delay to 10% of 5MHz.		- 555	115
Read to Idle	t _{RI}	Read Output or Write Current		600	
Write to Idle	twi			 600	ns
Chip Select to (WOK) Delay		Write Mode	 	 600	ns
Chip Enabled (O	N) t _{IWI}	VR/WH = 4V			
Chip Disabled (C			-	 1.5 600	μs
Chip Select to (WOK) Delay	VVII		 	 000	ns
Chip Enabled (C	ON) t ₂			1	μs
Chip Disabled (0	OFF) t ₁			2	μs
Chip Select to Write Select	1			 	
Verify Chip Enabled (C	' I			600	ns
Chip Disabled (C	OFF) W _{SVH}			600	ns
R/W Select to Write Current Delay					
Write Select	t _{RWW}	Measure delay to 90% of write Current. (CS = VL)		1 1	μs
Read Select	^t wrw	Measure delay to 10% of write		 '	-
R/W Select to Read Output	VVHVV	Current. (CS = VL)	<u> </u>	 600	ns
Delay		Measure delay to 90% of 5MHz Read Output. Waveform offset shift may be positive or negative			
		depending on Write Data Input conditions and should not be considered when taking			
Read Select	t WRR	measurement. CS = VL		600	ns
Write Select	^t RWR	Measure to 10% of 5MHz Read Output. CS = VL		1.5	μs
Head Select Switching Delay	^t HS	Measure 50% of HS to 90% Read Output or Write Current. CS = VL		1	μs
IMF Switching Time		Delay from 50% of Chip Select voltage (CS) to 50% (ON) or 50% (OFF) of final IMF voltage			
Chip Enabled (C	N) t _{IMF1}	respectively.	ŀ	600	ns
Chip Disabled (C	DFF) t _{IMF2}		 	 600	ns
Write OK Delay					
Unsafe to Safe D after Write Da (WD) Begins	Delay ta t _{UN1}	f DATA = 5MHz (Write Data)		600	ns
Safe to Unsafe Delay	t _{UN2}	Head opens or non-switching write data (WD) or no write current	0.6	 3.6	μs
Head Select Inpo Opened (Safe Unsafe Delay)	to [†] UN3			600	ns
Unsafe to Safe F to Write	- 0114	fDATA = 5MHz (Write Data)		3	μs
Safe to Unsafe V to Read	Write t UN5	fDATA = 5MHz (Write Data)		600	ns